

高速傳輸軟性基板用低粗糙度高彎折性電解銅箔

Very Low Profile of high bending property copper foil

型号: 3EC-M2S-HTE SP2 & 3EC-M2S-HTE SP3

高速傳輸軟性基板用低粗糙度高彎折性電解銅箔

Suitable for High Speed High Frequency and Fine pattern FPCBs design with excellent Bending Performance.

適合搭配MPI，信號傳輸損耗低，效果好

Excellent Signal Insertion lost performance with Modified PI.

剝離强度高

Good Bonding strength.

型号: 3EC-M2S-HTE SP2/SP3

Average crystal size: 6.5μm

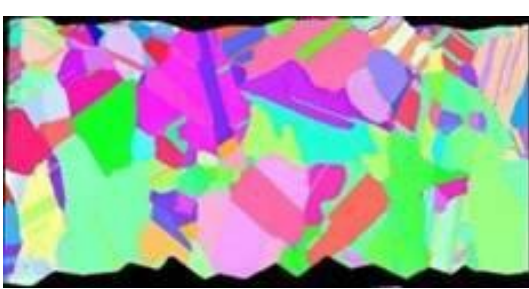


※After 180C, 1hr

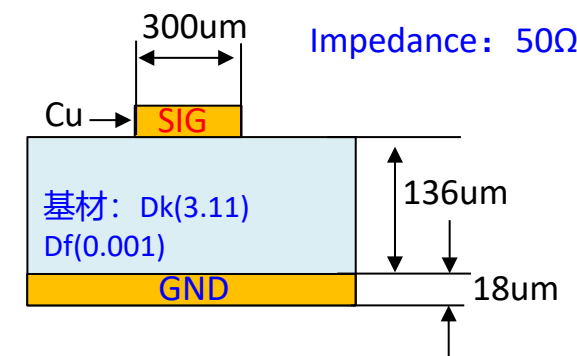
3μm

Class III

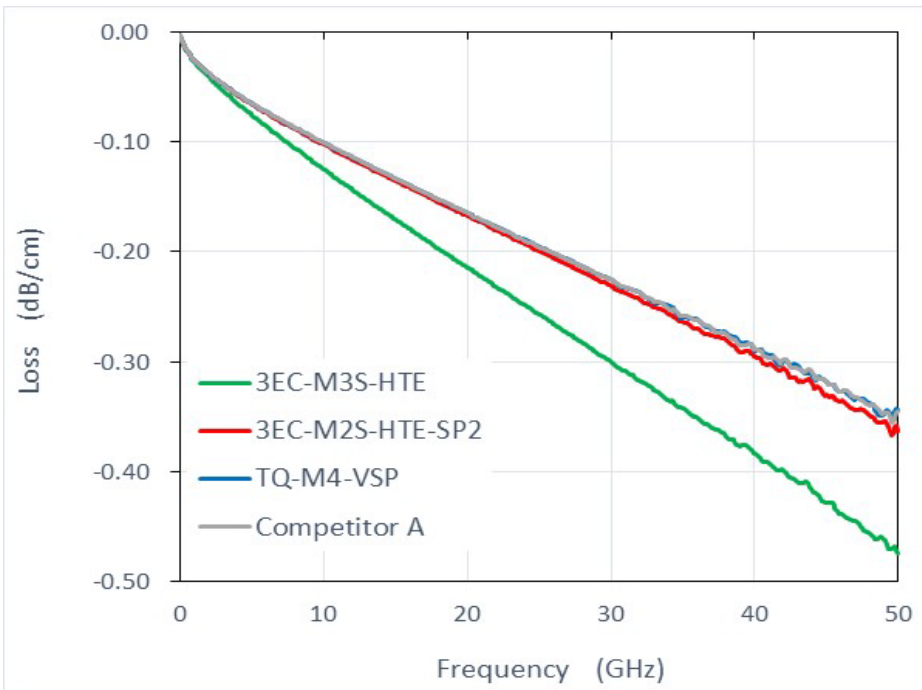
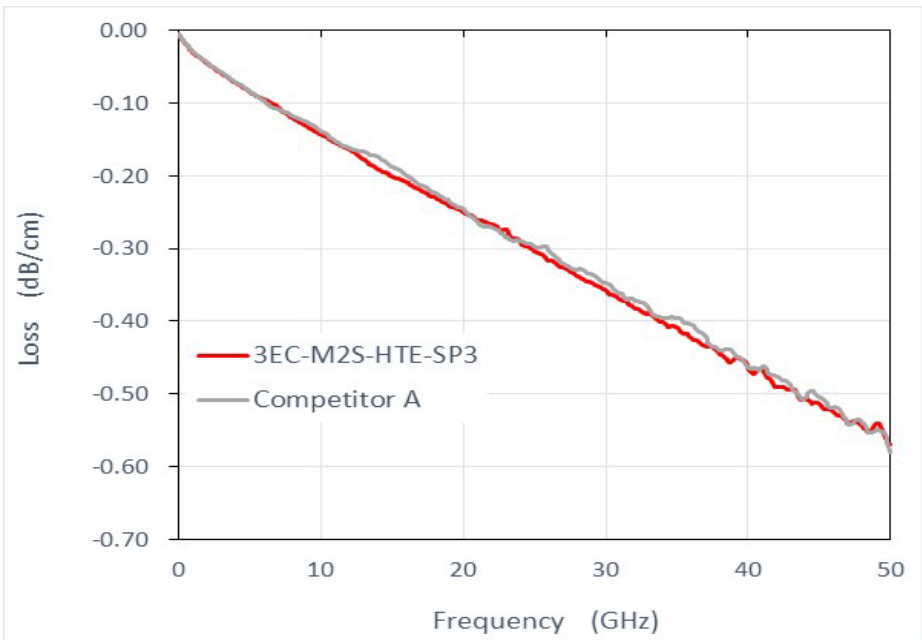
Average crystal size: 2.5μm



※After 180C, 1hr



Signal Insertion loss performance



		Surface roughness Lam. Side [μm]	Cross Section Image	Thickness [μm]
Normal Profile (Reference)	3EC-M3S-HTE	Rz 2.5		12 μm
Very Low Profile	3EC-M2S-HTE-SP2	Rz ~ 1.4		18 μm
SuperLow Profile	3EC-M2S-HTE-SP3	Rz 0.9~1.1		9μm, 12 μm, 18μm, 35μm, 70μm

* Mass Production in Mitsui Copper Foil Malaysia plant.

Excellent Copper Foil characteristic for Advance Flexible Board application.

三井金屬特有的高彎折性銅箔加上低粗糙度處理。

- Mitsui proprietary high bending property copper foil with very low profile treatment.

應用于高频高速上表現超低損耗。

- Improved Signal lost performance in High speed High frequency application.

產能高，足以滿足客戶量產需求。

- Good track record of reliable and advance production capability to fulfil customers' volume requirement.



三井金屬